

2010 EDITORIAL CALENDAR

2D/3D and DEVICE ASSEMBLY,
PACKAGING, INTERCONNECTS
and MATERIALS

WAFER-LEVEL PACKAGING
(WLP) BACK-END
PROCESSING ARTICLES

SHOW and CONFERENCE EXTRA
DISTRIBUTION

January/February 2010

Space: Jan 8

Materials: Jan 15

- 3D Technology Trends
- Sockets for Emerging Packaging
- Business: Buying New or Refurbished Equipment
- Wafer Thinning:
- Latest Market Demands in Die Sorting
- WLP--TSV Interconnects
- MEPTEC Q1 Symposium: San Jose, CA (Feb25)
- BiTS Workshop: Mesa, AZ (Mar. 7-10)
- IMAPS Device Pkg: Scottsdale, AZ (Mar 10-12)
- SEMICON China: Shanghai China (Mar 16-18)

March/April 2010

Space: Feb 24

Materials: Mar 3

- IC Packaging Foundries/OSATS Packaging Assembly and Test Directory
- Adhesives and Coatings
- Die Attach Films
- Thin Film Advancements
- Business: Obsolescence Management
- Wafer Bumping Services
- APEX Expo: Las Vegas, NV (Apr. 6-8)
- MEPTEC Q2 MEMS Symposium: San Jose, CA (May 20)

May/June 2010

Space: Apr 26

Materials: May 3

- Die and Flip Chip Bonders
- Thermal Control
- AOI, Acoustic, and X-Ray Inspection
- Business: Outsourcing Office Management
- ECTC/ITHERM: Las Vegas, NV (Jun 2-3)

July/August 2010

Space: Jun 11

Materials: Jun 18

- Dispensing , Encapsulants & Underfill
- IC Package Design
- Photovoltaic Assembly
- Business: Outfitting a Clean Room
- Wafer Handling of Thinned Wafers
- SEMICON West: San Francisco (Jul 13-15)
- SEMICON Taiwan: Taipei, Taiwan (Sept 8-10)

September/October 2010

Space: Aug 27

Materials: Sep 3

- MEMS for Medical Applications
- Nanotechnology Materials
- Stencil Printing
- Wire Bonding
- Singulation & Dicing
- Business: Improving First Pass Yields
- WLP - Testing
- MEPTEC/SMTA Medical Electronics: Tempe, AZ (Sept 22- 23)
- ATE: Rosemont, IL (Sept 28-30)
- IWLPC - Intl Wafer-Level Packaging Conference Santa Clara, CA (Oct 11-14)
- SEMICON Europa: Dresden, Germany (Oct 19-21)
- SMTA International: Orlando, FL (Oct 24-28)
- IMAPS: Raleigh, NC (Oct 31-Nov 4)
- ITC - International Test Conference: Austin, TX (Nov 2-4)
- KGD Workshop Santa Clara, CA (TBD)

November/December 2010

Space: Oct 26

Materials: Nov 2

- 3D Packaging Applications
- Reflow Soldering
- Automotive Package Applications
- Test and Burn-in Sockets Vendor Directory
- HDI Substrates
- Business: Personnel Training and Certification
- Wet and Plasma Cleaning
- Wafer Probing
- SEMICON Japan : Chiba, Japan (Dec 1-3)
- MEPTEC Q4 Semiconductor Roadmaps: Santa Clara, CA (Nov 10)

Notes: Editorial calendar topics and distribution are subject to change without notice and are contingent on logistics and magazine production.
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